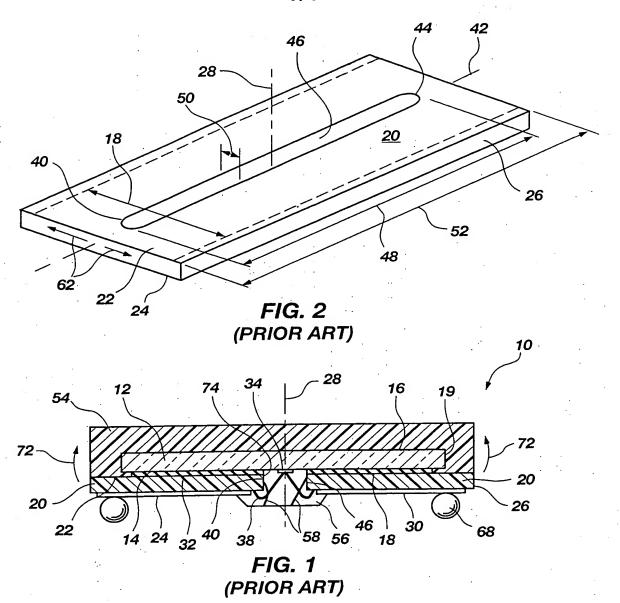
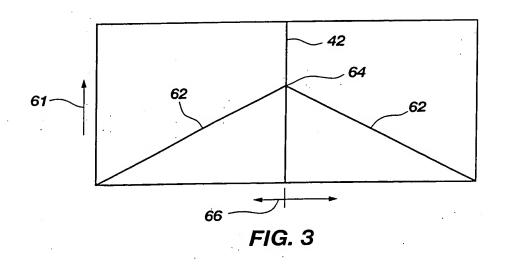
TITLE: SEMICONDUCTOR DIE CONFIGURED FOR USE WITH INTERPOSER SUBSTRATES HAVING REINFORCED INTERCONNECT SLOTS

Inventor: Blaine J. Thurgood Docket No.: 2269-5520.2US

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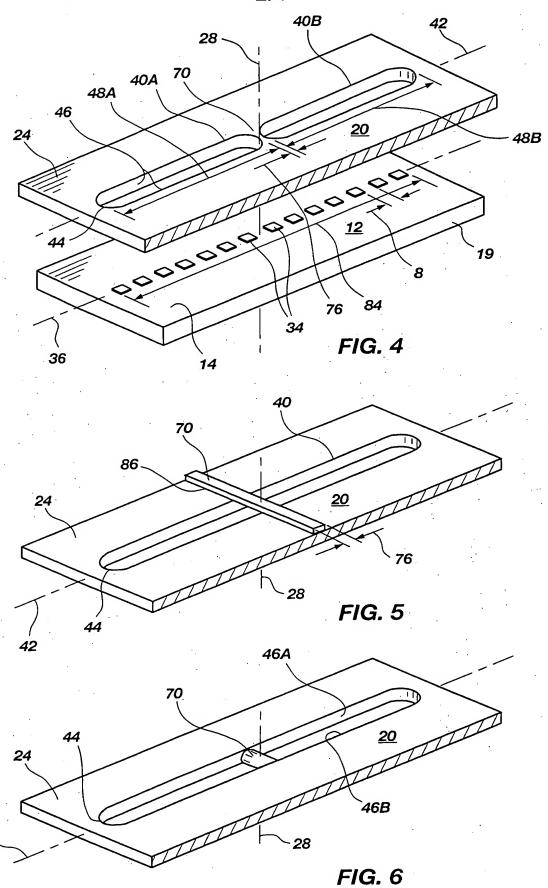




## TITLE: SEMICONDUCTOR DIE CONFIGURED FOR USE WITH INTERPOSER SUBSTRATES HAVING REINFORCED INTERCONNECT SLOTS

Inventor: Blaine J. Thurgood Docket No.: 2269-5520.2US





## TITLE: SEMICONDUCTOR DIE CONFIGURED FOR USE WITH INTERPOSER SUBSTRATES HAVING REINFORCED

INTERCONNECT SLOTS Inventor: Blaine J. Thurgood Docket No.: 2269-5520.2US

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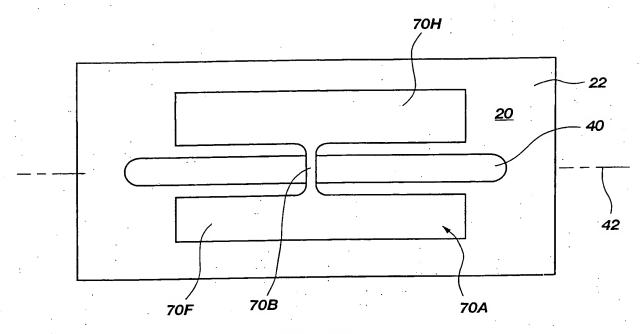


FIG. 5A

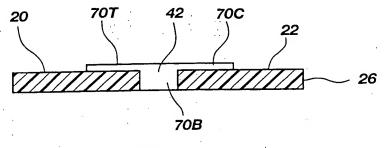


FIG. 7

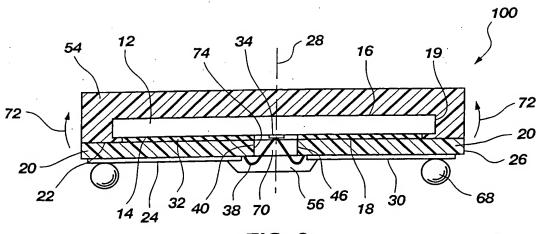


FIG. 8

## TITLE: SEMICONDUCTOR DIE CONFIGURED FOR USE WITH INTERPOSER SUBSTRATES HAVING REINFORCED INTERCONNECT SLOTS

Inventor: Blaine J. Thurgood Docket No.: 2269-5520.2US

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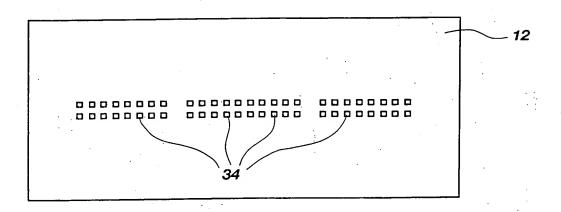


FIG. 9

